FDMC8360L Rev. C1

June 2013

FDMC8360L N-Channel Shielded Gate Power Trench[®] MOSFET 40 V, 80 A, 2.1 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 2.1 m Ω at V_{GS} = 10 V, I_D = 27 A
- Max $r_{DS(on)}$ = 3.1 m Ω at V_{GS} = 4.5 V, I_D = 22 A
- High performance technology for extremely low
 r_{DS(on)}
- Termination is Lead-free

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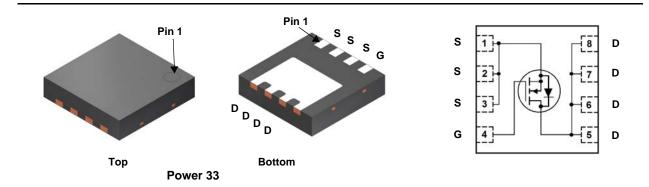
- 100% UIL Tested
- RoHS Compliant

General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench[®] process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Application

DC-DC Conversion



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter					Ratings		Units	
V _{DS}	Drain to Source Voltage			40		V			
V _{GS}	Gate to Source Voltage				±20		V		
ID	Drain Current	-Continuous	1	Г _С = 25 °С		80			
		-Continuous	-	T _A = 25 °C	(Note 1a)	27		А	
		-Pulsed			(Note 4)	240			
E _{AS}	Single Pulse Av	valanche Energy			(Note 3)	294		mJ	
P _D	Power Dissipat	ion	7	Г _С = 25 °С		54		14/	
	Power Dissipat	ion	-	Г _А = 25 °С	(Note 1a)	2.3		W	
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150		°C			
Thermal Ch	naracteristics								
R _{0JC}	Thermal Resistance, Junction to Case (Note 1)) 2.3		°C/W			
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient (Note 1a)				53		0/00		
Package M	arking and O	dering Inform	ation						
Device Ma	arking	Device	Package	Ree	el Size	Tape Width	Qua	ntity	
FDMC83	360L F	DMC8360L	Power33	1	13 "	12 mm 3		3000 units	

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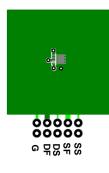
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N-Channel Shielded Gate Power Trench
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Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu\text{A}$, referenced to 25 °C		22		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32 V, V _{GS} = 0 V			1	μA
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Chara	acteristics					
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$	1.0	1.6	3.0	V
$\Delta V_{GS(th)}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °C		-6		mV/°C
r _{DS(on)}		V _{GS} = 10 V, I _D = 27 A		1.6	2.1	mΩ
	Static Drain to Source On Resistance	V _{GS} = 4.5 V, I _D = 22 A		2.3	3.1	
D3(01)						
D3(01)		$V_{GS} = 10 \text{ V}, \ \text{I}_{D} = 27 \text{ A}, \ \text{T}_{J} = 125 \ ^{\circ}\text{C}$		2.2	2.9	
9 _{FS}	Forward Transconductance	$V_{GS} = 10 \text{ V}, \text{ I}_D = 27 \text{ A}, \text{ T}_J = 125 \text{ °C}$ $V_{DD} = 5 \text{ V}, \text{ I}_D = 27 \text{ A}$		2.2 138	2.9	S
9 _{FS}	Forward Transconductance Characteristics Input Capacitance	V _{DD} = 5 V, I _D = 27 A			2.9	S pF
{9⊧s} Dynamic	Characteristics	$V{DD} = 5 \text{ V}, I_D = 27 \text{ A}$ 		138		
g _{FS} Dynamic C _{iss}	Characteristics	V _{DD} = 5 V, I _D = 27 A		138 4140	5795	pF
g _{FS} Dynamic C _{iss} C _{oss}	Characteristics Input Capacitance Output Capacitance	$V_{DD} = 5 \text{ V}, I_D = 27 \text{ A}$ 	0.1	138 4140 1230	5795 1725	pF pF
g _{FS} Dynamic C _{iss} C _{oss} C _{rss} R _g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DD} = 5 \text{ V}, I_D = 27 \text{ A}$ 	0.1	138 4140 1230 36	5795 1725 60	pF pF pF
g _{FS} Dynamic C _{iss} C _{oss} C _{rss} R _g Switchin	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance	$V_{DD} = 5 \text{ V}, I_D = 27 \text{ A}$ 	0.1	138 4140 1230 36	5795 1725 60	pF pF pF
g _{FS} Dynamic C _{iss} C _{oss} C _{rss} R _g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics	$V_{DD} = 5 \text{ V}, I_D = 27 \text{ A}$ 	0.1	138 4140 1230 36 0.9	5795 1725 60 2.7	pF pF pF Ω
g _{FS} Dynamic C _{iss} C _{oss} C _{rss} R _g Switchin	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 27 \text{ A}$ $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1 MHz	0.1	138 4140 1230 36 0.9 15	5795 1725 60 2.7 28	pF pF pF Ω
gFS Dynamic C _{iss} C _{oss} C _{rss} R _g Switching t _{d(on)} t _r	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance Characteristics Turn-On Delay Time Rise Time	$V_{DD} = 5 V, I_D = 27 A$ $V_{DS} = 20 V, V_{GS} = 0 V,$ f = 1 MHz $V_{DD} = 20 V, I_D = 27 A,$	0.1	138 4140 1230 36 0.9 15 6.7	5795 1725 60 2.7 28 14	pF pF pF Ω ns
$\begin{array}{c} g_{FS} \\ \hline \textbf{Dynamic} \\ C_{iss} \\ C_{oss} \\ C_{rss} \\ \hline \textbf{R}_{g} \\ \hline \textbf{Switchin} \\ \hline \textbf{switchin} \\ \hline \textbf{t}_{d(on)} \\ \hline \textbf{t}_{r} \\ \hline \textbf{t}_{d(off)} \\ \hline \textbf{t}_{f} \\ \end{array}$	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 27 \text{ A}$ $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$ $V_{DD} = 20 \text{ V}, \text{ I}_{D} = 27 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$ $V_{GS} = 0 \text{ V to } 10 \text{ V}$	0.1	138 4140 1230 36 0.9 15 6.7 38	5795 1725 60 2.7 28 14 60	pF pF pF Ω ns ns
$\begin{array}{c} g_{FS} \\ \hline \textbf{Dynamic} \\ C_{iss} \\ \hline C_{oss} \\ \hline C_{rss} \\ \hline R_g \\ \hline \textbf{Switchin} \\ \hline \textbf{switchin} \\ \hline t_{d(on)} \\ \hline t_r \\ \hline t_{d(off)} \\ \hline \end{array}$	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 27 \text{ A}$ $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$ $V_{DD} = 20 \text{ V}, \text{ I}_{D} = 27 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$ $V_{GS} = 0 \text{ V to } 10 \text{ V}$ $V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 20 \text{ V},$	0.1	138 4140 1230 36 0.9 15 6.7 38 5.3	5795 1725 60 2.7 28 14 60 11	pF pF Ω ns ns ns ns
$\begin{array}{c} g_{FS} \\ \hline \textbf{Dynamic} \\ \hline \textbf{C}_{iss} \\ \hline \textbf{C}_{oss} \\ \hline \textbf{C}_{rss} \\ \hline \textbf{R}_{g} \\ \hline \textbf{Switchin} \\ \hline \textbf{switchin} \\ \hline \textbf{t}_{d(on)} \\ \hline \textbf{t}_{r} \\ \hline \textbf{t}_{d(off)} \\ \hline \textbf{t}_{f} \\ \hline \textbf{Q}_{g(TOT)} \end{array}$	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 27 \text{ A}$ $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$ $V_{DD} = 20 \text{ V}, \text{ I}_{D} = 27 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$	0.1	138 4140 1230 36 0.9 15 6.7 38 5.3 57	5795 1725 60 2.7 28 14 60 11 80	pF pF pF Ω ns ns ns ns ns

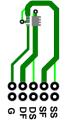
V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 27 A$	(Note 2)	0.8	1.3	V
V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 1.9 A$	(Note 2)	0.7	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 27 A, di/dt = 100 A/μs		49	80	ns
Q _{rr}	Reverse Recovery Charge			29	46	nC

Notes:

1. $R_{0,JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{0,JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper

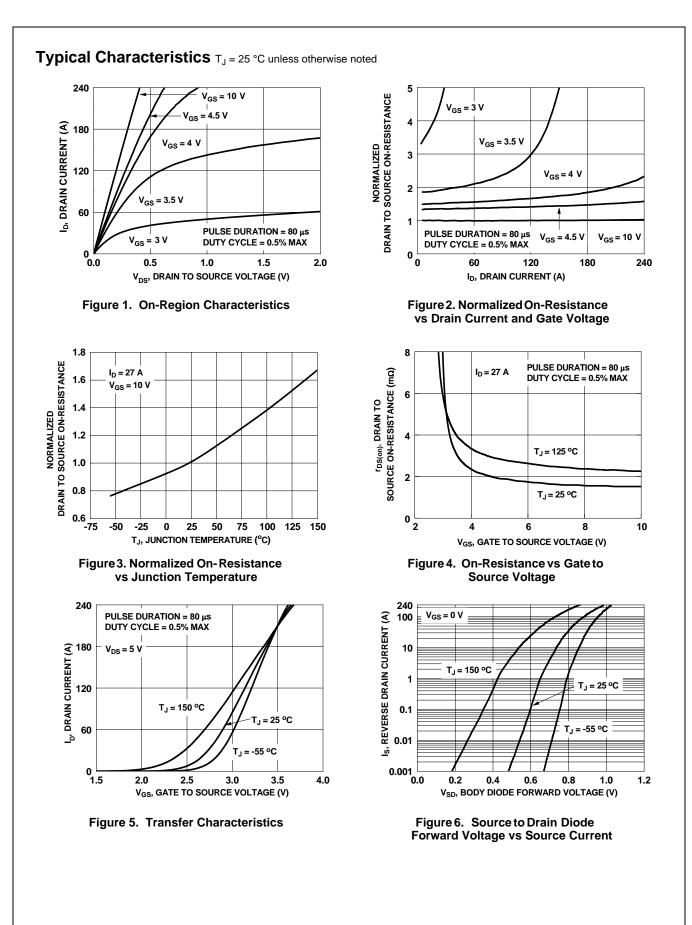


b. 125 °C/W when mounted on a minimum pad of 2 oz copper

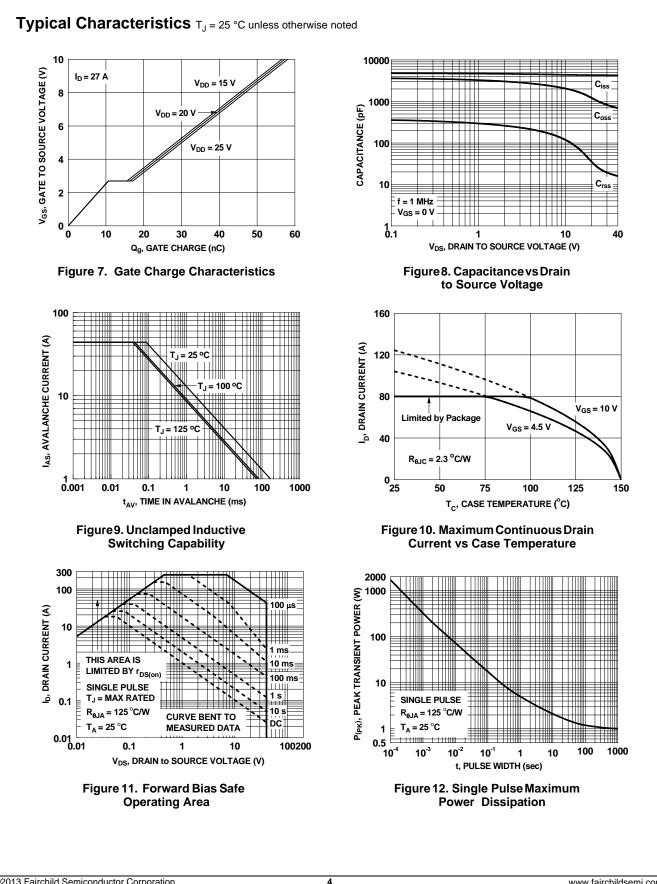
2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.

3. E_{AS} of 294 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 14 A, V_{DD} = 40 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 44 A.

4. Pulsed Id limited by junction temperature, td<=100 μ S, please refer to SOA curve for more details.

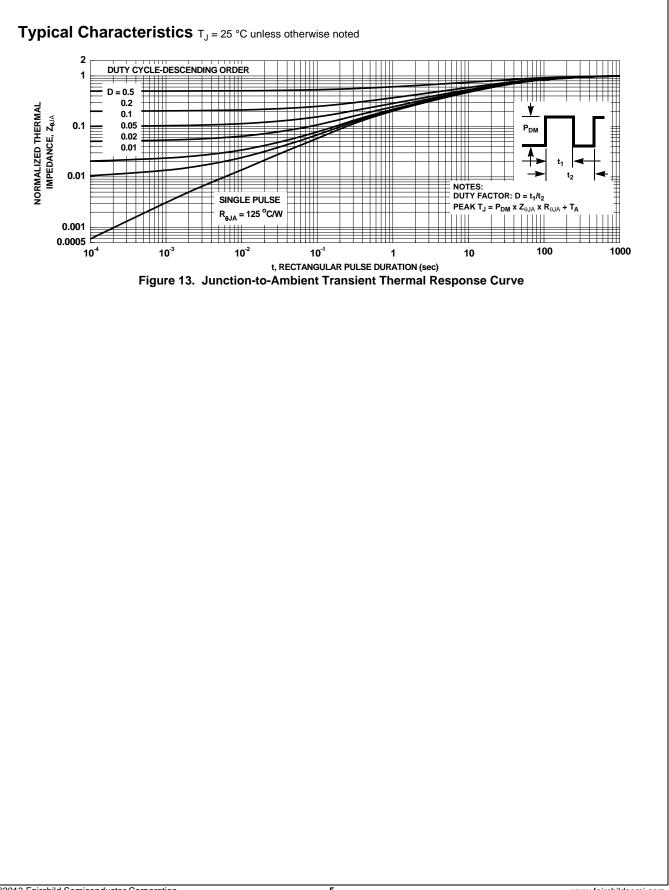


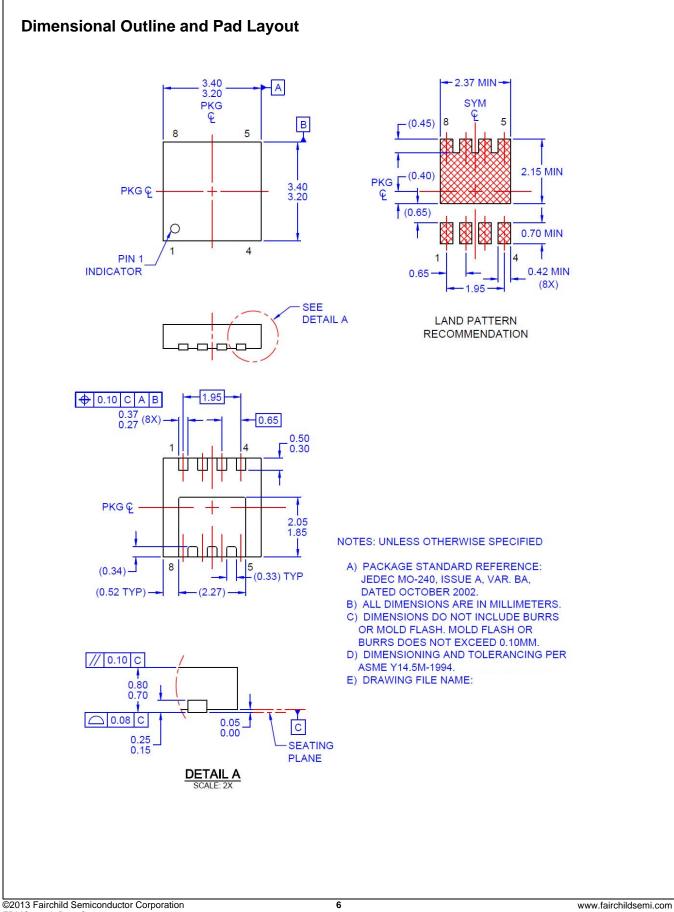
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